



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-09-30
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32U385CGU6Q	62MI*454XXXZ	A	998Z	2024-09-30
Amount	Unit of measure	Unit type	ST ECOPACK grade	
102	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	7x7	48	Flat	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	62MI*454XXXZ		101.9840		6000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	3.489	mg	supplier	die	Silicon (Si)	7440-21-3		3.298	mg	945164	32334.86296
				supplier	metallization	Aluminium (Al)	7429-90-5		0.021	mg	6053	207.0782695
				supplier	metallization	Copper (Cu)	7440-50-8		0.063	mg	18037	617.0610848
				supplier	metallization	Nickel (Ni)	7440-02-0		0.000	mg	121	4.139512738
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.011	mg	3147	107.661542
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	726	24.83707643
				supplier	metallization	Tungsten (W)	7440-33-7		0.000	mg	121	4.139512738
				supplier	Passivation	Silicon Nitride	12033-89-5		0.015	mg	4358	149.0908803
				supplier	Passivation	Silicon Oxide	7631-86-9		0.078	mg	22273	761.9782415
				supplier	Organic Compounds	Acrylic resin	Proprietary		0.036	mg	70000	348.6822905
Glue Epoxy (EN4900GC)	Other Organic Materials	0.508	mg	supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.010	mg	20000	99.62351158
				supplier	Organic Compounds	Butadiene copolymer	Proprietary		0.008	mg	15000	74.71763369
				supplier	Organic Compounds	Acrylate	Proprietary		0.027	mg	54000	268.9834813
				supplier	Organic Compounds	Epoxy resin	Proprietary		0.015	mg	30000	149.4352674
				supplier	Organic Compounds	Peroxide	Proprietary		0.004	mg	8000	39.84940463
				supplier	Organic Compounds	Additive	Proprietary		0.009	mg	18000	89.66116042
				supplier	Metals	Silver	7440-22-4		0.399	mg	785000	3910.22283
				supplier	Organic Compounds	Epoxy Resin A	Proprietary		0.744	mg	21000	7296.588759
Encapsulation (EME- G631BQ)	Other Organic Materials	35.435	mg	supplier	Organic Compounds	Epoxy Resin B	Proprietary		0.744	mg	21000	7296.588759
				supplier	Organic Compounds	Phenol Resin	Proprietary		1.772	mg	50000	17372.83038
				supplier	Glass	Silica(Amorphous)A	60676-86-0		27.994	mg	790000	274490.72
				supplier	Glass	Silica(Amorphous)B	7631-86-9		3.295	mg	93000	32313.4645
				supplier	Organic Compounds	Metal Hydroxide	Proprietary		0.709	mg	20000	6949.132151
				supplier	Organic Compounds	Carbon Black	1333-86-4		0.177	mg	5000	1737.283038
				supplier	Metals	Copper	7440-50-8		0.458	mg	965500	4487.441064
				supplier	Metals	Palladium	7440-05-3		0.015	mg	31000	144.0814842
Bonding Wire (Cu)	Bonding Wire	0.474	mg	supplier	Metals	Gold	7440-57-5		0.002	mg	3500	16.26726434
				supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	10570.28991
				supplier	Metals	Copper	7440-50-8		55.946	mg	917140	548571.9638
Plating anode (Sn)	Other inorganic materials	1.078	mg	supplier	Metals	Nickel	7440-02-0		1.373	mg	22500	13457.99898
				supplier	Metals	Silicon	7440-21-3		0.159	mg	2600	1555.146549
Leadframe (C7025 + Ag)	Copper & its alloys	61.000	mg	supplier	Metals	Magnesium	7439-95-4		0.070	mg	1150	687.8532813
				supplier	Metals	Silver	7440-22-4		3.453	mg	56610	33860.32544